



PRODUCT IDENTIFICATION

JRPI 1206 P - 100 M
 | | | |
Type Size Material Inductance Tol.

FEATURES

1. Shielded construction.
2. Capable of corresponding high frequency
3. Low loss realized with low DCR.
4. High performance (Isat) realized by metal dust core.
5. Ultra low buzz noise, due to composite construction.
6. 100% Lead(Pb)-Free and RoHS compliant.
7. Operating temperature -40~+125°C
(Including self - temperature rise)

Marking and Date code:

Marking ex: 10 (μH) → 100

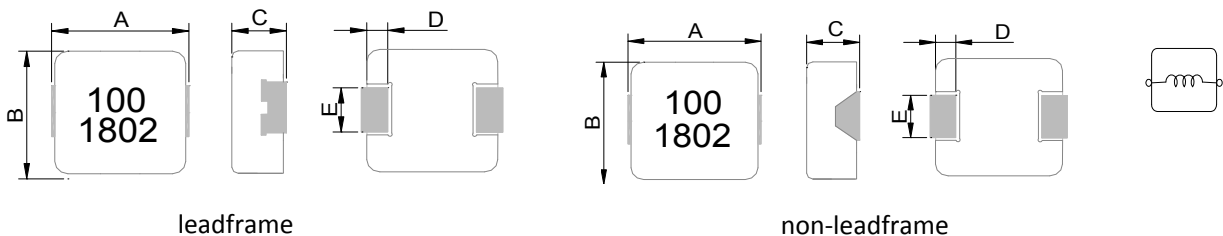
Date code

18 02 → year and weekly

APPLICATIONS

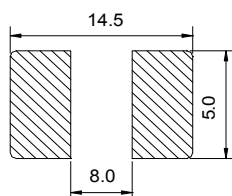
1. DC/DC converters in distributed power systems.
2. DC/DC converter for Field Programmable Gate Array(FPGA).
3. Battery powered devices.
4. Thin type on-board power supply module for exchanger.
5. VRM for server.
6. High current, low profile POL converters.
7. PDA/notebook/desktop/server and battery powered devices.

DIMENSIONS (mm)



印字:黑色100及D/C 1802 (18年,02週期)(依實際生產日期而定)

Recommend PC Board Pattern



Note:

1. PCB layout is referred to standard IPC-7351B
2. The above PCB layout reference only.
3. Recommend solder paste thickness at 0.15mm and above.

Part No.	Size (mm)				
	A	B	C	D	E
JRPI 1206P	13.5 ± 0.5	12.6 ± 0.2	5.7 ± 0.3	2.3 ± 0.3	See spec table

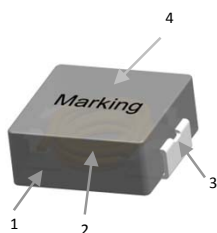
SERIES LIST

No.	Part No.	L	RDC		Isat		Irms		E	Type
		(μ H)	Typ.	Max.	Typ	Max	Typ	Max	(mm) ± 0.3	
1	JRPI 1206P-R36M	0.36 $\pm$ 20%	0.65	0.8	70.0	60.0	60.0	50.0	4.7	non-leadframe
2	JRPI 1206P-1R5M	1.5 $\pm$ 20%	2.40	3.0	32.0	27.0	28.0	24.0	4.0	non-leadframe
3	JRPI 1206P-2R2M	2.2 $\pm$ 20%	3.70	4.3	28.0	24.0	25.0	21.0	4.7	leadframe
4	JRPI 1206P-3R3M	3.3 $\pm$ 20%	5.30	6.5	28.0	24.0	21.0	18.0	4.7	leadframe
5	JRPI 1206P-4R7M	4.7 $\pm$ 20%	7.00	8.4	23.0	19.5	19.0	16.0	4.7	leadframe
6	JRPI 1206P-8R2M	8.2 $\pm$ 20%	13.5	16.0	17.0	15.5	13.5	12.0	4.7	leadframe
7	JRPI 1206P-100M	10 $\pm$ 20%	15.5	18.6	16.0	14.5	12.0	10.5	4.7	leadframe
8	JRPI 1206P-150M	15 $\pm$ 20%	24.0	29.0	10.0	9.0	10.0	8.5	4.7	leadframe
9	JRPI 1206P-220M	22 $\pm$ 20%	31.2	37.5	9.0	8.0	8.0	7.0	4.7	leadframe
10	JRPI 1206P-330M	33 $\pm$ 20%	56.0	68.0	7.8	6.7	6.5	5.5	4.7	leadframe
11	JRPI 1206P-470M	47 $\pm$ 20%	76.0	88.0	6.7	5.5	5.2	4.5	4.7	leadframe
12	JRPI 1206P-680M	68 $\pm$ 20%	103	124	5.8	5.0	4.5	3.7	4.7	leadframe
13	JRPI 1206P-101M	100 $\pm$ 20%	162	195	5.0	4.0	3.2	2.8	4.7	leadframe
14	JRPI 1206P-151M	150 $\pm$ 20%	270	325	4.1	3.2	2.6	2.2	4.7	leadframe

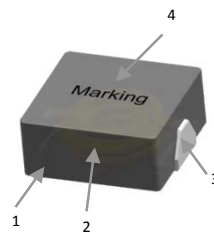
Note:

1. Test Frequency: 100KHz /1V
2. All test data referenced to 25°C ambient
3. Saturation Current (Isat) will cause L0 to drop approximately 30%.
4. Heat Rated Current (Irms) will cause the coil temperature rise approximately ΔT of 40°C
5. The part temperature (ambient + temp rise) should not exceed 125°C under worst case operating conditions.
Circuit design, component, PCB trace size and thickness, airflow and other cooling provisions all affect the part temperature. Part temperature should be verified in the end application.
6. Irms Testing : Temperature rise is highly dependent on many factors including pcb land pattern, trace size, and proximity to other components. Therefore temperature rise should be verified in application conditions.
7. Rated DC Current : The less value which is Irms or Isat.

Materials



leadframe



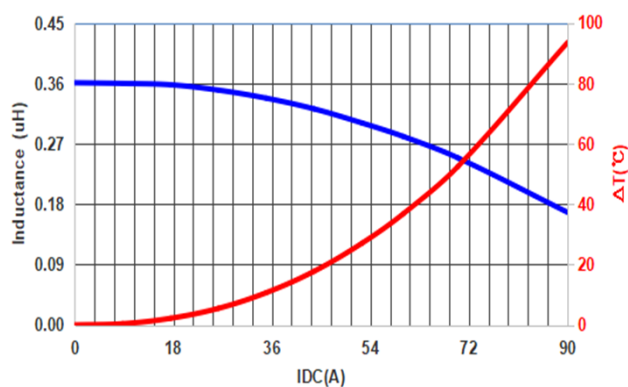
non-leadframe

NO	Items	Materials
1	Core	Alloy Powder
2	Wire	Polyester Wire or equivalent
3	Clip	100% Pb free solder(Ni+Sn---Plating)
4	Ink	Halogen-free ketone

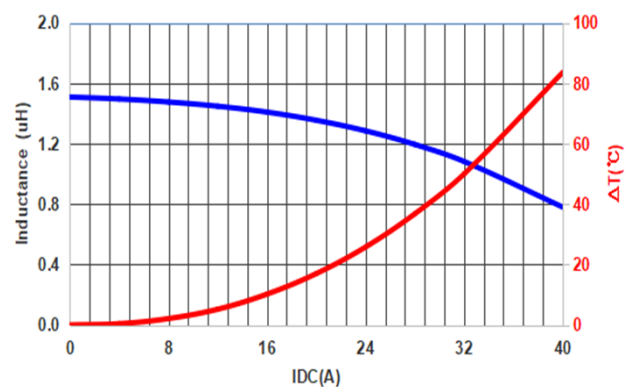
NO	Items	Materials
1	Core	Alloy Powder
2	Wire	Polyester Wire or equivalent
3	Solder	100% Pb free solder
4	Ink	Halogen-free ketone

TYPICAL PERFORMANCE CURVES

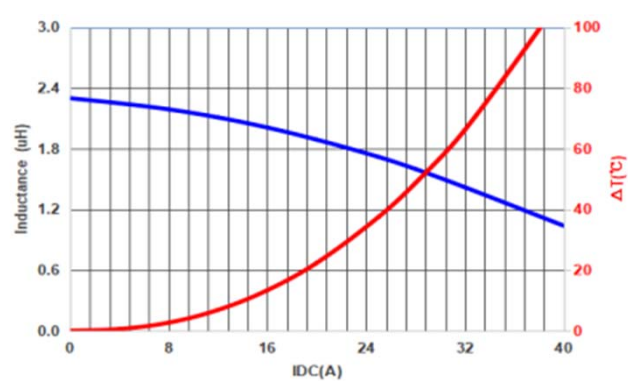
JRPI 1206P-R36



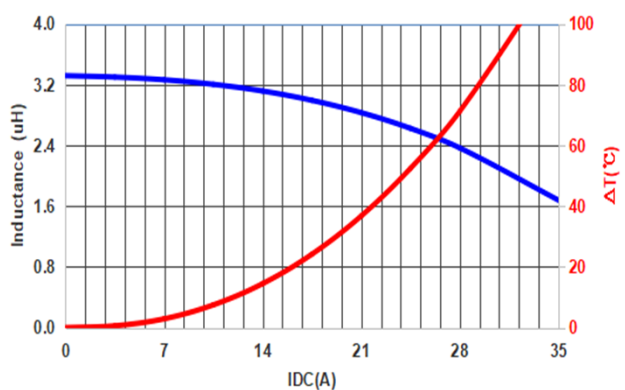
JRPI 1206P-1R5



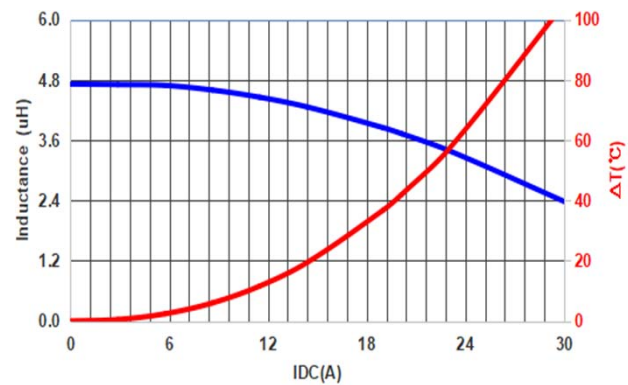
JRPI 1206P-2R2



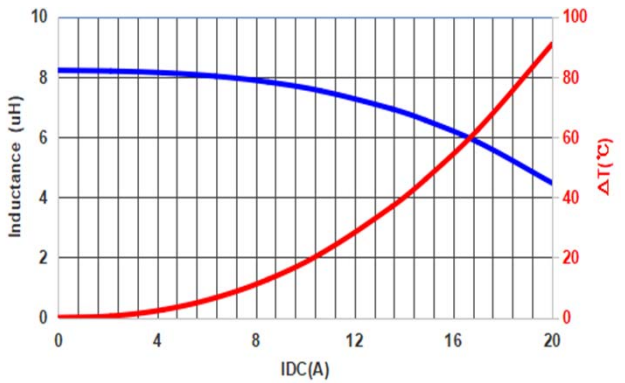
JRPI 1206P-3R3



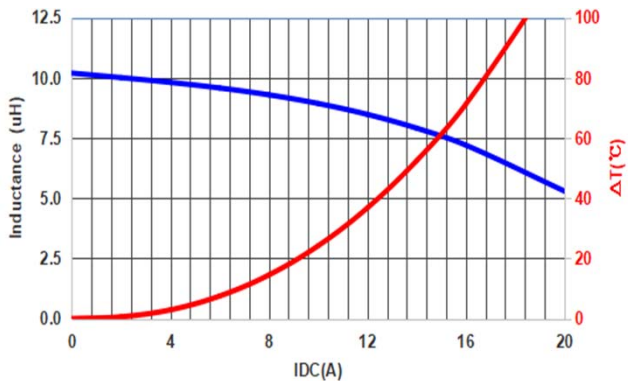
JRPI 1206P-4R7



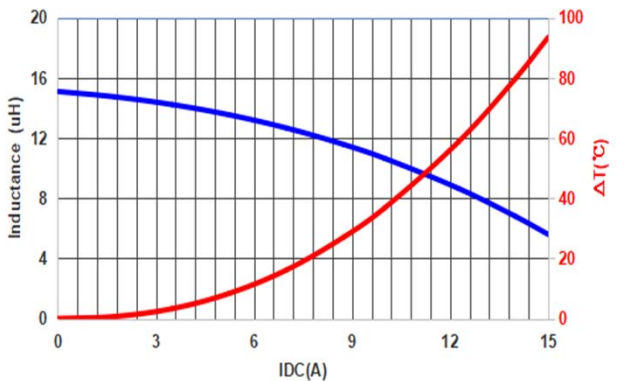
JRPI 1206P-8R2



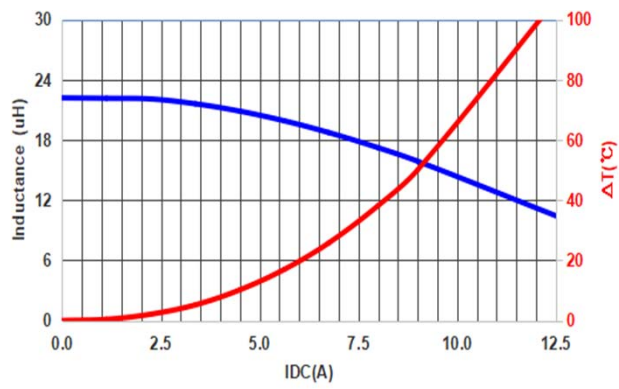
JRPI 1206P-100



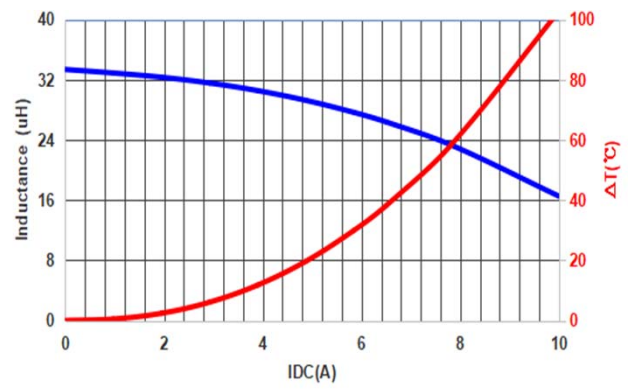
JRPI 1206P-150



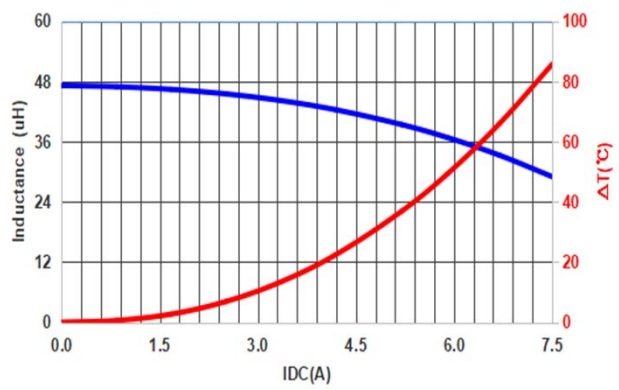
JRPI 1206P-220



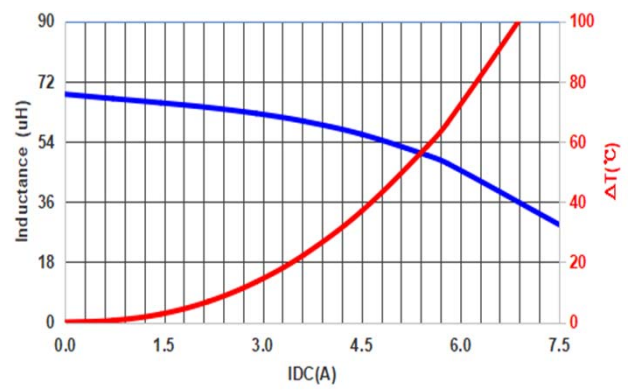
JRPI 1206P-330



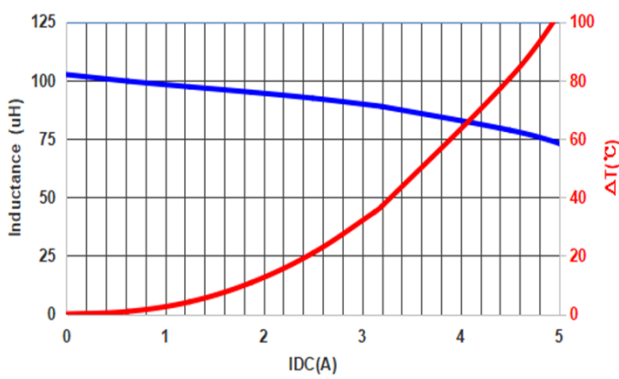
JRPI 1206P-470



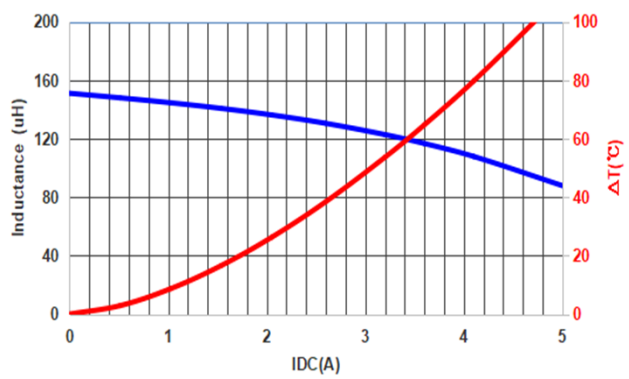
JRPI 1206P-680



JRPI 1206P-101

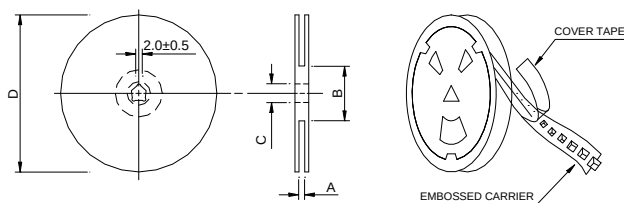


JRPI 1206P-151



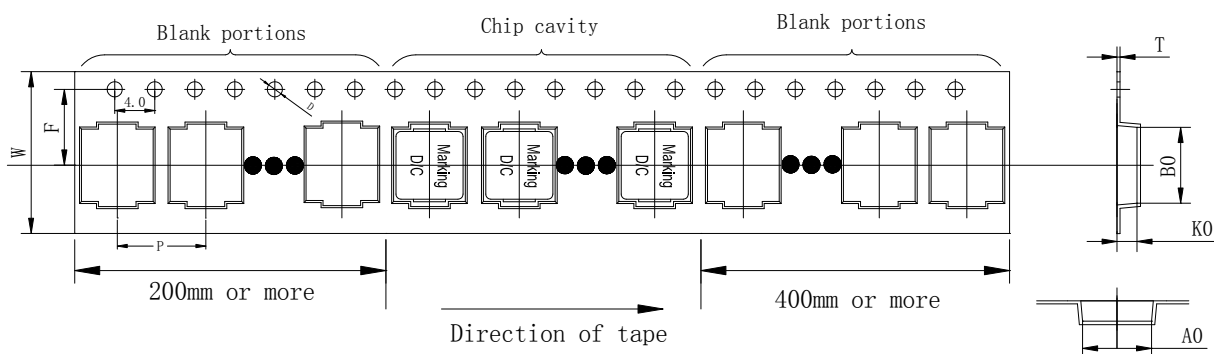
Packaging Information

• Reel Dimension



Type	A(mm)	B(mm)	C(mm)	D(mm)
13"x24mm	$24.4 \pm 2/-0$	100 ± 2	$13 \pm 0.5/-0.2$	330

• Tape Dimension



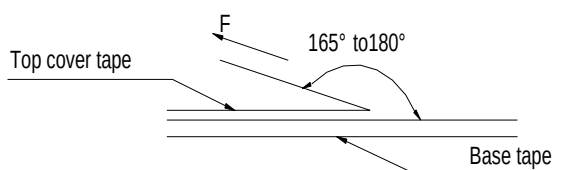
Ao(mm)	Bo(mm)	Ko(mm)	P(mm)	W(mm)	F(mm)	t(mm)	D(mm)
12.9 ± 0.1	14.1 ± 0.1	6.5 ± 0.1	16.0 ± 0.1	24 ± 0.3	11.5 ± 0.1	0.35 ± 0.05	1.5 ± 0.1

• Packaging Quantity

Size	Reel
JRPI 1206P	500

• Tearing Off Force

The force for tearing off cover tape is 10 to 130 grams in the arrow direction under the following conditions (referenced ANSI/EIA-481-D-2008 of 4.11 standard)



Tearing Speed mm	Room Temp. ($^{\circ}\text{C}$)	Room Humidity (%)	Room atm (hPa)
$300 \pm 10\%$	5~35	45~85	860~1060

■ Application Notice

- Storage Conditions(component level)

To maintain the solderability of terminal electrodes:

1. Products meet IPC/JEDEC J-STD-020E standard-MSL, level 1.
2. Temperature and humidity conditions: Less than 40°C and 60% RH.
3. Recommended products should be used within 12 months form the time of delivery.
4. The packaging material should be kept where no chlorine or sulfur exists in the air.

- Transportation

1. Products should be handled with care to avoid damage or contamination from perspiration and skin oils.
2. The use of tweezers or vacuum pick up is strongly recommended for individual components.
3. Bulk handling should ensure that abrasion and mechanical shock are minimized.